

SPECIFICATION



- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL21B223KBCNFNC
- Description : CAP, 22nF, 50V, ±10%, X7R, 0805

A. Samsung Part Number

			<u>CL</u>	<u>21</u>	<u>B</u>	<u>223</u>	<u>K</u>	<u>B</u>	<u>C</u>	<u>N</u>	<u>F</u>	<u>N</u>	<u>c</u>					
			1	2	3	4	(5)	6	1	8	9	10	1					
1	Series	Samsu	na Mult	i-lave	r Cer	amic (ana	citor										
\sim	Size		(inch c	-				± 0.1		mm		W:	1.25	± 0.1	m	m		
			\	,			-	-						-				
3	Dielectric	X7R					8	Inne	r ele	ctroc	le		Ni					
4	Capacitance	22	nF					Tern	ninat	tion			Cu					
5	Capacitance	±10	%					Plati	ng				Sn 10	0%	(F	b Free)	
	tolerance						9	Proc	luct				Produ	ict for F	POV	VER ap	plication	
6	Rated Voltage	50	V				10	Spee	cial				Rese	rved fo	r fut	ure use	:	
\bigcirc	Thickness	0.85	± 0.1	mm			1	Pack	cagir	ng			Cardb	oard T	уре	, 7" ree	I	

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1ktz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.025 max.							
Insulation	10,000Mohm or 500Mohm· <i>µ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X7R							
Characterisitcs	(From -55 $^\circ$ to 125 $^\circ$ C, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 $^{\circ}$ C for 10~30sec.)						
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition				
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours \times 3 direction (x, y, z)				
Moisture	Capacitance change : within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR : 500Mohm or 25Mohm $\cdot \mu F$					
	Whichever is Smaller					
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR : 1000Mohm or 50Mohm · μF					
	Whichever is Smaller	1000+48/-0hrs				
Temperature	Capacitance change : within ±7.5%	1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C				
		\rightarrow Max. operating temperature \rightarrow 25 °C				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.